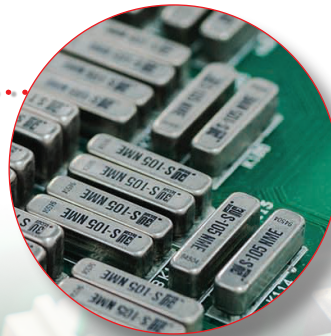


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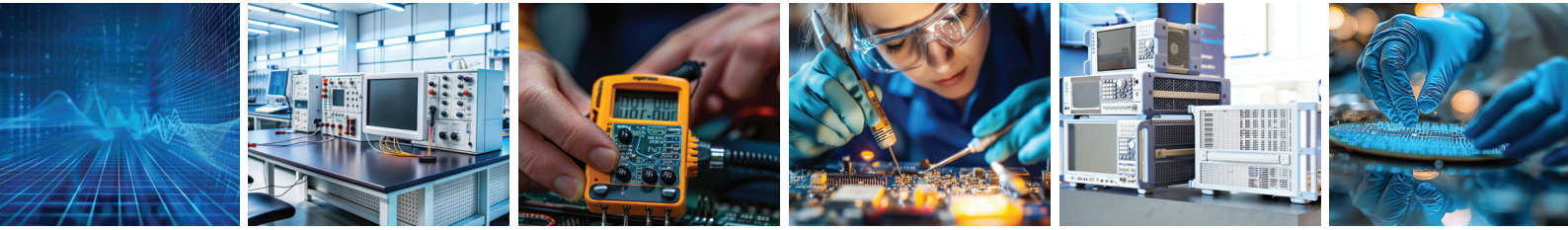
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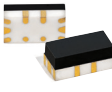

















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HIGH FREQUENCY / RF & HIGH DENSITY REED RELAYS



HIGH FREQUENCY

OPERATING CHARACTERISTICS	CRF SERIES	U SERIES	C SERIES	M SERIES	MT SERIES	MH SERIES
Special Feature:	 Ceramic base for low voltage offset	 Series with the smallest SMD mounting area for 8GHz	 1 Form A with excellent shielding and 7GHz RF performance	 1A and 2A Form with excellent shielding and 6 GHz RF performance	 1 and 2 changeover-like form in a small SMD package	 Miniature vertical changeover SMD relay
Coil Voltage VDC:	3, 5	3.3, 5	3.3, 5	5, 12	3.3, 5, 12	3.3, 5, 12
Contact Form:	1A	1A	1A	1A, 2A	1T, 2T, 1A+1B	1T (changeover)
Rated Power Max. W:	10	3	10	10	10	10
Switching Voltage Max. VDC:	170	100	100	100	100	100
Switching Current Max. A:	0.5	0.2	0.5	0.5	0.5	0.5
Carry Current Max. A:	1	0.2	1	1	1	1
Insulation Resistance Typ. Ω:	>10 ¹¹	>10 ¹²	>10 ¹¹	>10 ¹¹	>10 ¹¹	>10 ¹¹
Dielectric Strength Min. VDC:	1500	150	200	200	200	200
RF CHARACTERISTICS						
Insertion Loss -3dB drop off point GHz:	~ 7 GHz	~ 8 GHz	~ 7 GHz	~ 6 GHz	~ 4 GHz	~ 3 GHz
MECHANICAL SPECIFICATIONS						
Lead Style:	SMD Non-BGA	SMD J-Lead	SMD, Gull/J-Lead	SMD, Gull/J-Lead	SMD J-Lead	SMD J-Lead
Mounting Area L x W mm:	8.6 x 4.4	7.95 x 4.67	8.9 x 4.67	9.9 x 4.67 10.16 x 6.7	10.16 x 7.62 10.0 x 11.3	9.9 x 5.08
						
DATASHEET LINK						

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HIGH FREQUENCY/RF & HIGH DENSITY REED RELAYS



HIGH DENSITY

OPERATING CHARACTERISTICS	CRR SERIES	MF SERIES	MFS SERIES	UMS SERIES	MS SERIES
Special Feature:	 Ceramic base for low voltage offset	 Vertical square shape for high density assembly	 Vertical square shape	 Ultra Miniature THT relay with integrated magnetic shield	 Miniature SIL THT relay for high density assembly
Coil Voltage VDC:	3, 5	5, 12	3, 5, 12	5	5, 12
Contact Form:	1A	1A	1A, 2A, 1C (1A+1B)	1A	1A
Rated Power Max. W:	10	5	10	10	10
Switching Voltage Max. VDC:	170	50	100	170	200
Switching Current Max. A:	0.5	0.2	0.5	0.5	0.5
Carry Current Max. A:	1	0.75	1	1	1
Insulation Resistance Typ. Ω:	>10 ¹¹	10 ¹⁰	>10 ¹¹	>10 ¹²	>10 ¹²
Dielectric Strength Min. VDC:	1500	150	200	1500	1500
MECHANICAL SPECIFICATIONS					
Lead Style:	SMD Non-BGA	THT	THT	THT/SIP	THT/SIP
Mounting Area L x W mm:	8.6 x 4.4	4.35 x 4.35	4.9 x 4.9	6.85 x 3.6	15.2 x 3
					
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